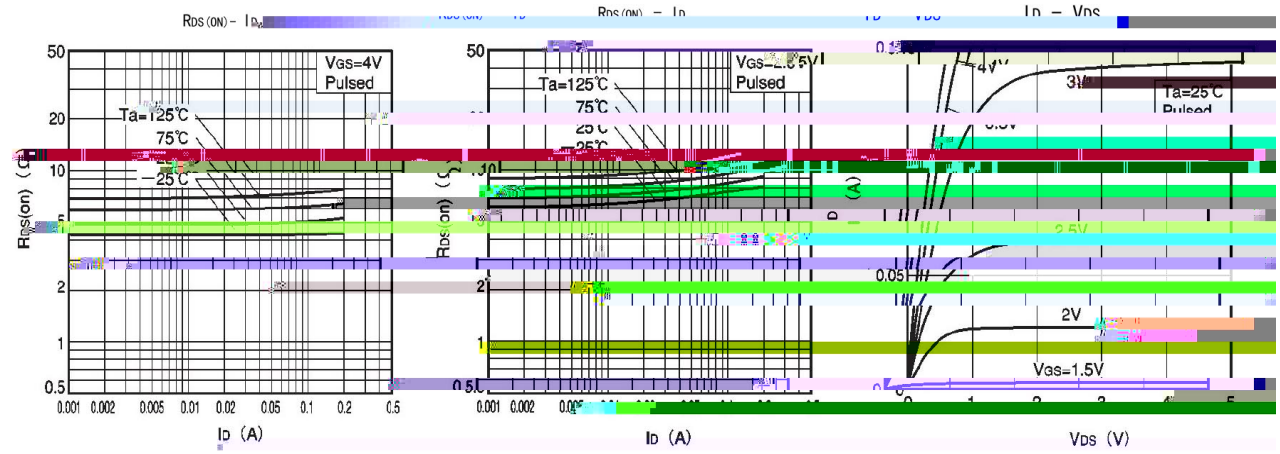
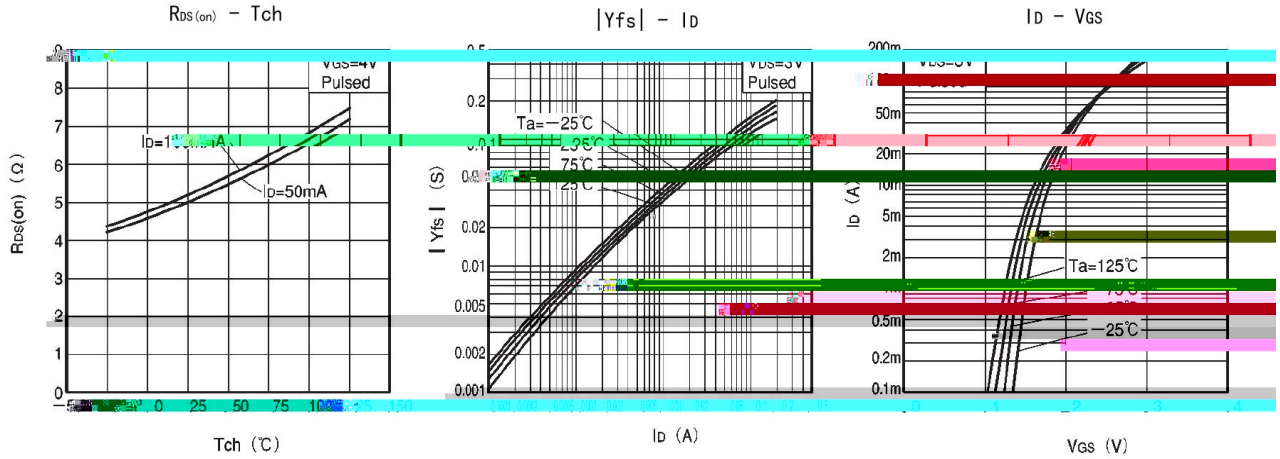
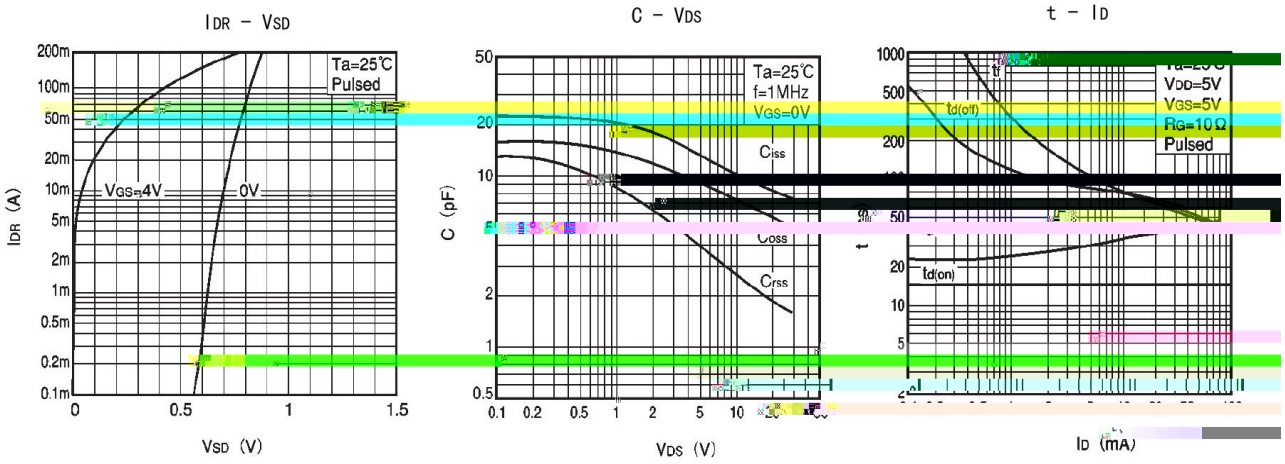
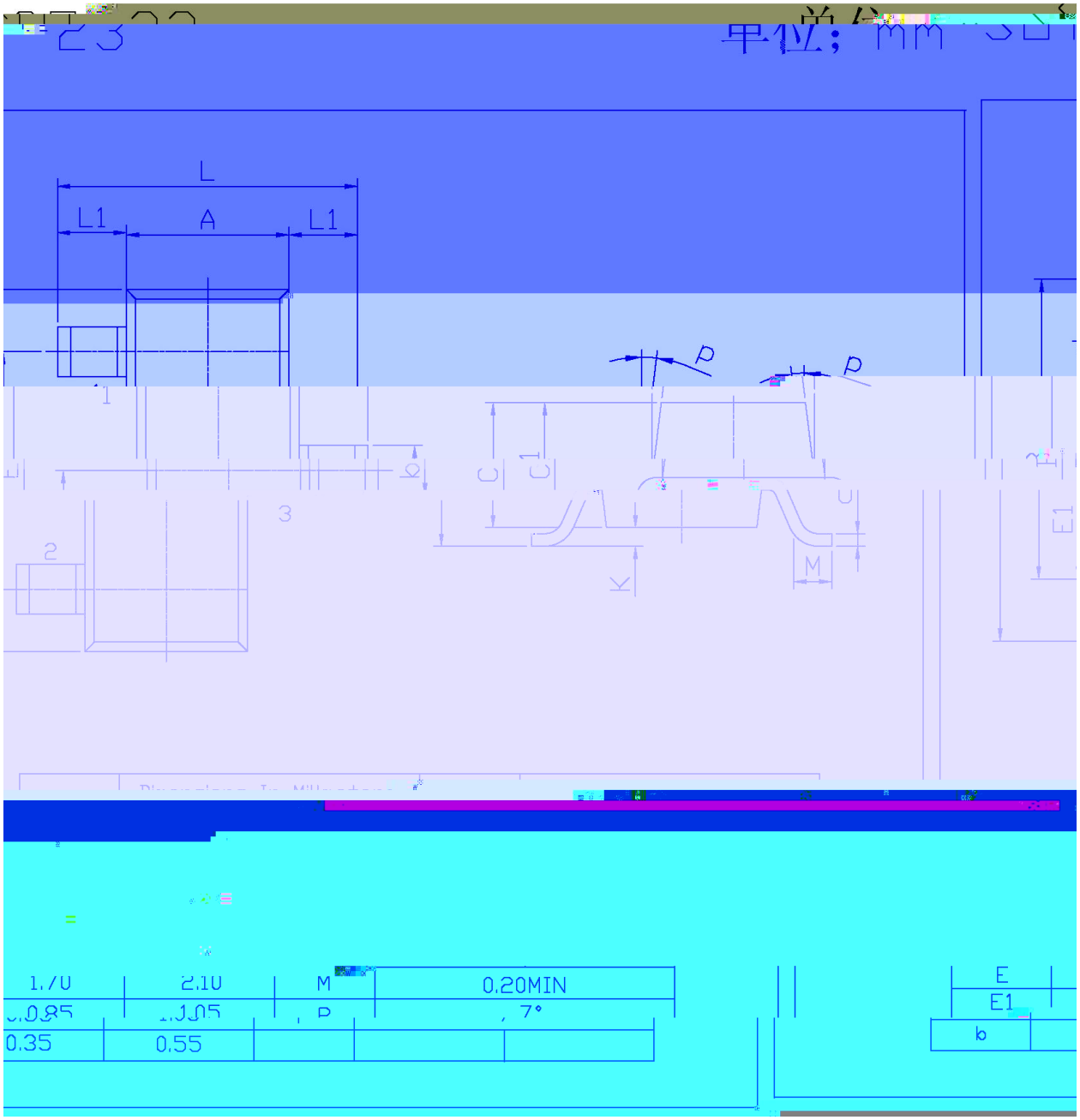
/ Electrical Characteristic Curve



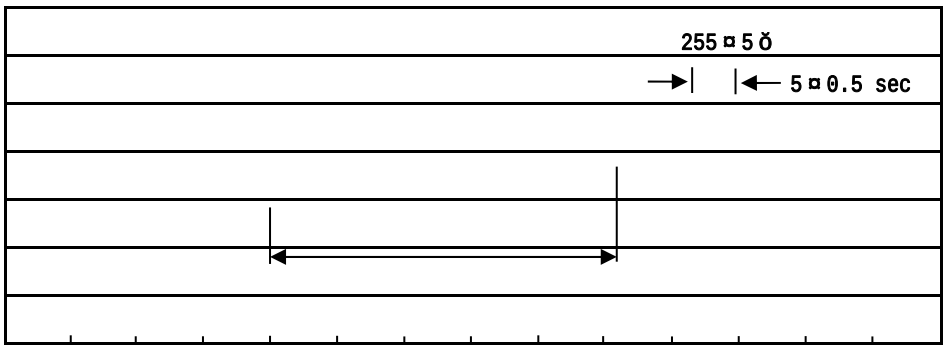




/ Package Dimensions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب χ

1	أ	150	200		ژ 60	120sec;	1.Preheating:150~200 , Time:60~120sec.
2		255±5		ژ	۸	5±0.5sec;	2.Peak Temp.:255±5 , Duration:5±0.5sec.
3		۱	ھ	2	10	/sec.	3. Cooling Speed: 2~10 /sec.

Note:

/ Resistance to Soldering Heat Test Conditions

χ 260±5 ژ χ 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

` Ь / REEL

Package Type	Units					Dimension		(unit mm³)

/ Notices